

# **nanoNET TRX Complementary Dispersive Delay Line (CDDL) DS1804C**

Datasheet

Version 5.00

NA-04-0143-0276-5.00



## Document Information

Document Title: nanoNET CDDL DS1804C Datasheet  
Document Version: 5.00  
Published (yyyy-mm-dd): 2007-08-21  
Current Printing: 2007-8-21, 12:46 pm  
Document ID: NA-04-0143-0276-5.00  
Document Status: Released

### Disclaimer

Nanotron Technologies GmbH believes the information contained herein is correct and accurate at the time of release. Nanotron Technologies GmbH reserves the right to make changes without further notice to the product to improve reliability, function or design. Nanotron Technologies GmbH does not assume any liability or responsibility arising out of this product, as well as any application or circuits described herein, neither does it convey any license under its patent rights.

As far as possible, significant changes to product specifications and functionality will be provided in product specific Errata sheets, or in new versions of this document. Customers are encouraged to check the Nanotron website for the most recent updates on products.

### Trademarks

nanoNET<sup>®</sup> is a registered trademark of Nanotron Technologies GmbH. All other trademarks, registered trademarks, and product names are the sole property of their respective owners.

This document and the information contained herein is the subject of copyright and intellectual property rights under international convention. All rights reserved. No part of this document may be reproduced, stored in a retrieval system, or transmitted in any form by any means, electronic, mechanical or optical, in whole or in part, without the prior written permission of Nanotron Technologies GmbH.

Copyright © 2007 *Nanotron Technologies GmbH*.

## Life Support Policy

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Nanotron Technologies GmbH customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Nanotron Technologies GmbH for any damages resulting from such improper use or sale.

### Electromagnetic Interference / Compatibility

Nearly every electronic device is susceptible to electromagnetic interference (EMI) if inadequately shielded, designed, or otherwise configured for electromagnetic compatibility.

To avoid electromagnetic interference and/or compatibility conflicts, do not use this device in any facility where posted notices instruct you to do so. In aircraft, use of any radio frequency devices must be in accordance with applicable regulations. Hospitals or health care facilities may be using equipment that is sensitive to external RF energy.

With medical devices, maintain a minimum separation of 15 cm (6 inches) between pacemakers and wireless devices and some wireless radios may interfere with some hearing aids. If other personal medical devices are being used in the vicinity of wireless devices, ensure that the device has been adequately shielded from RF energy. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.



**CAUTION!** Electrostatic Sensitive Device. Precaution should be used when handling the device in order to prevent permanent damage.

## Table of Contents

<b>1</b>	<b>Definition of the CDDL</b>	<b>1</b>
<b>2</b>	<b>CDDL Detailed Description</b>	<b>3</b>
2.1	Balanced Filter (Top View)	3
2.2	Balanced Filter (Bottom View)	3
2.3	Housing Layout Dimensions	4
2.4	Pad Landing (Top View) – Proposal	4
2.5	CDDL on PC board (Top View)	5
2.6	Package Dimensions	5
<b>3</b>	<b>Measurements</b>	<b>6</b>
3.1	Test Board for Measurements	6
3.2	Target Specifications and Measurement Results (03/2003)	6
<b>4</b>	<b>Absolute Maximum Ratings</b>	<b>8</b>
<b>5</b>	<b>Tape and Reel Information</b>	<b>9</b>
5.1	Reel Dimensions	9
5.2	Tape Dimensions	9
5.2.1	Tape Specifications	9
5.2.2	Tape Running Direction	10
5.2.3	Leader Part and Vacant Position Specifications	10
5.2.4	Tape Dimensions	10
<b>6</b>	<b>Ordering Information</b>	<b>11</b>

Intentionally Left Blank

## 1 Definition of the CDDL

The *Complementary Dispersive Delay Line* (CDDL) uses a highly sophisticated SAW (*Surface Acoustic Wave*) filter device that incorporates two filters within a single device. It is required for the operation of the *nanoNET TRX Transceiver*.

While most devices have two ports, the CDDL consists of three ports, as shown below.

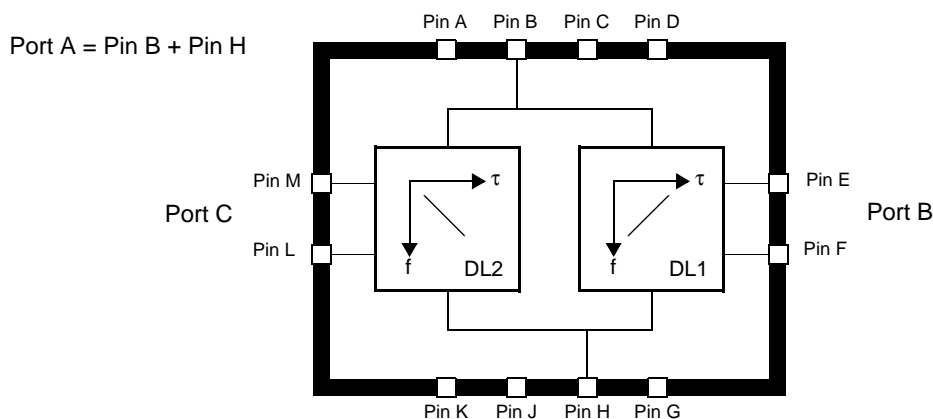


Figure 1: Complementary Dispersive Delay Line schematic

### Upchirp and Downchirp

Port A is the common input port. The group delay of the filter from the input to one of the outputs is characteristic for these filters.

The respective impulse response for the dispersive Delay Line 2 (DL2) is an *Upchirp* (Linear frequency modulation, where frequency increases in time).

The other output is complementary to this, meaning that the impulse response for Delay Line 1 (DL1) is a *Downchirp* (Linear frequency modulation, where frequency decreases in time).

Within the *nanoNET* system, the CDDL is responsible for distinguishing between two possible incoming signals generated by another *nanoNET TRX Transceiver*. This received signal is either an Upchirp or a Downchirp. Both of these signals have the same center frequency and the same bandwidth so that the difference occurs only in the phase information.

This phase information is enough for the CDDL to compress a pulse at one output port and expand it at the other (that is, to extend the incoming signal to the doubled duration). In this way the CDDL acts like a matched filter for one of the possible transmitted pulses.

### Balanced Mode

Also, within the *nanoNET* system, the CDDL is directly connected to an RF transceiver. As this transceiver has a differential output and input, the filter is used in a **balanced mode**.

According to this balanced mode, the housing has 6 signal pins – two on each side and two in the center on opposite sides. The detailed pinning is described on the *Balanced Filter (Bottom View)* on page 3 and *Pad Landing (Top View) – Proposal* on page 4. All other pins are connected to ground and at least one of them should be connected with the ground of the PC board.

Table 1: CDDL pin description

Pin Number	Description
A	GND
B	A <sub>p</sub> , (port A, line P)
C	GND
D	GND
E	B <sub>n</sub> , (port B, line N)
F	B <sub>p</sub> , (port B, line P)
G	GND
H	A <sub>n</sub> , (port A, line N)
J	GND
K	GND
L	C <sub>p</sub> , (port C, line P)
M	C <sub>n</sub> , (port C, line N)

## 2 CDDL Detailed Description

### 2.1 Balanced Filter (Top View)

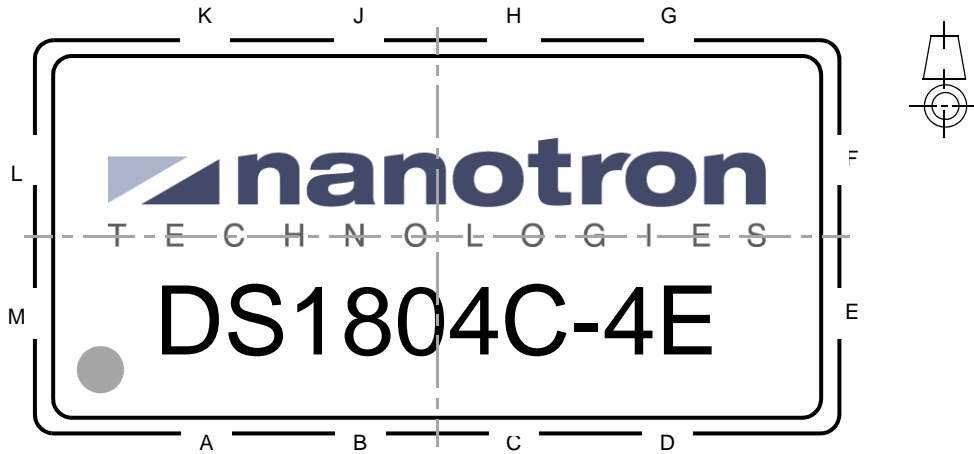


Figure 2: CDDL balanced filter - top view

### 2.2 Balanced Filter (Bottom View)

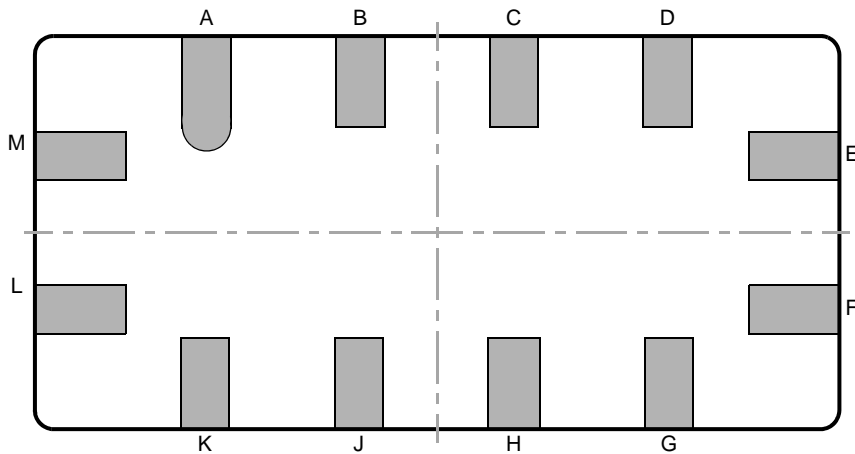


Figure 3: CDDL balanced filter - bottom view

The types of signals for each pin of the CDDL housing is described in the following table.

Table 2: Pin signal types

Type	Label
Signal	B, E, F, H, L, M
Ground	A, C, D, G, I, K, S/R <sup>1</sup>

1. S/R means seal ring

### 2.3 Housing Layout Dimensions

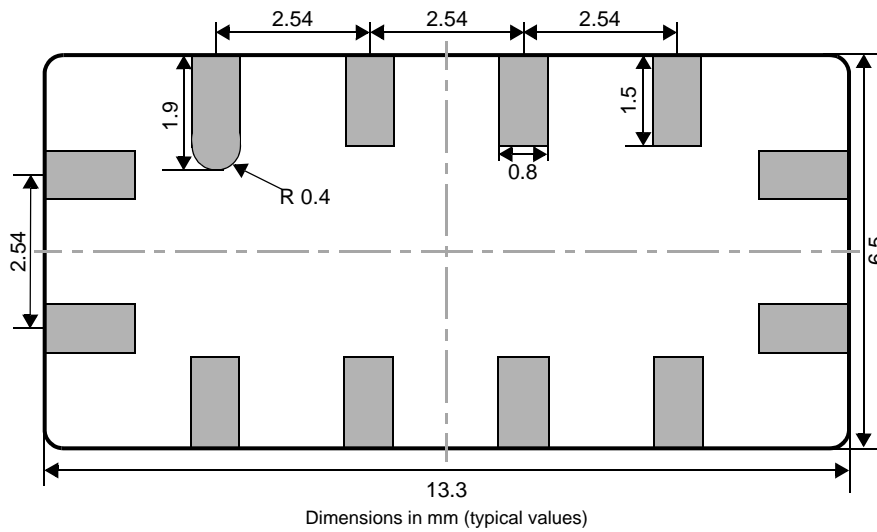


Figure 4: CDDL - bottom view measures

### 2.4 Pad Landing (Top View) – Proposal

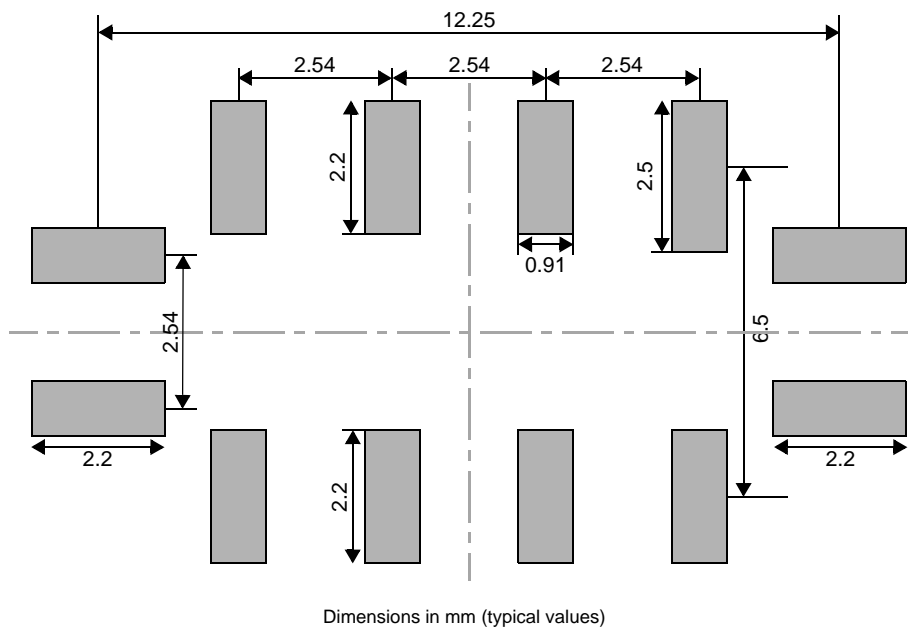


Figure 5: CDDL pad landing



## 2.5 CDDL on PC board (Top View)

In the illustration below, the signal pins are connected to strip lines. They are designed with a width of 0.91 mm to be able to go through two pins to connect both lines of port A from one side. On a typical PC board (FR4 of height 0.51 mm and copper thickness 35 μm,  $\epsilon_r = 4.7$ ) the impedance of these lines is about 50 Ω.

**Note:** The ground pins, which are connected with ground, are not shown in the following figure.

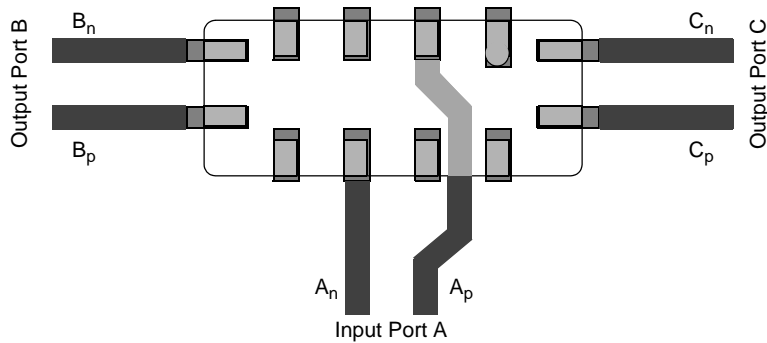


Figure 6: CDDL test board connections

## 2.6 Package Dimensions

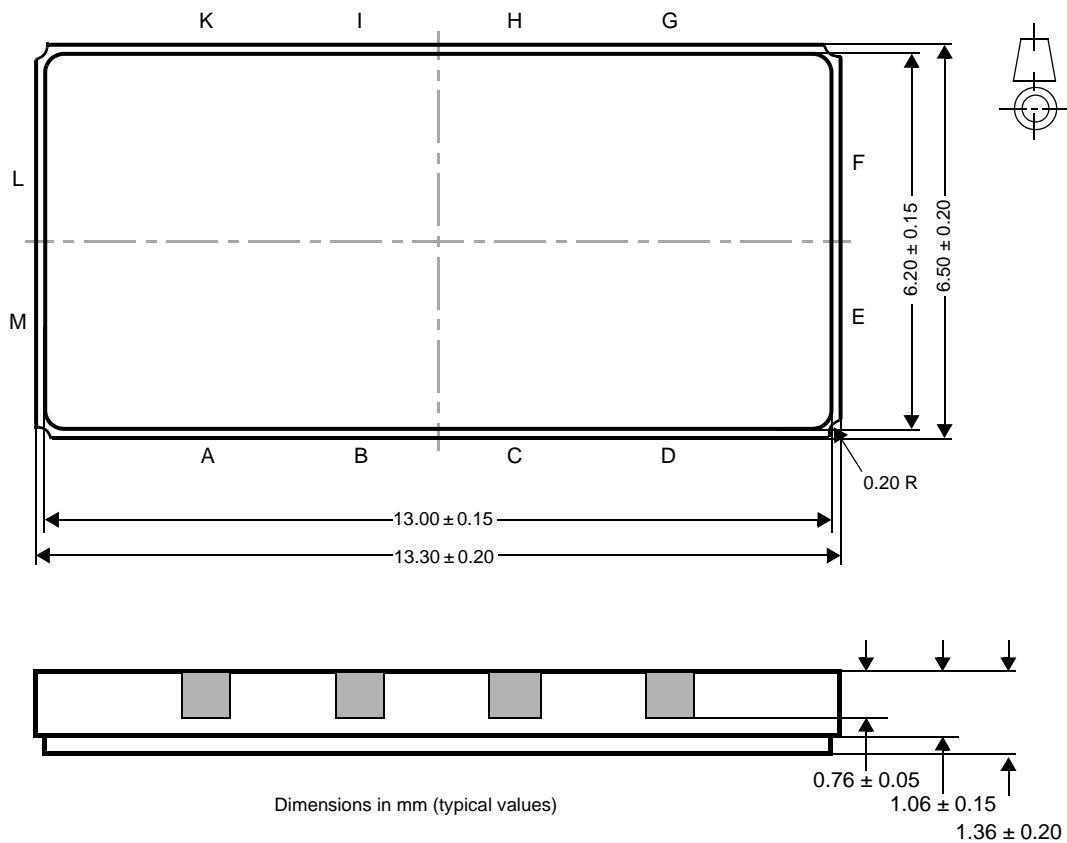


Figure 7: CDDL package dimensions

### 3 Measurements

#### 3.1 Test Board for Measurements

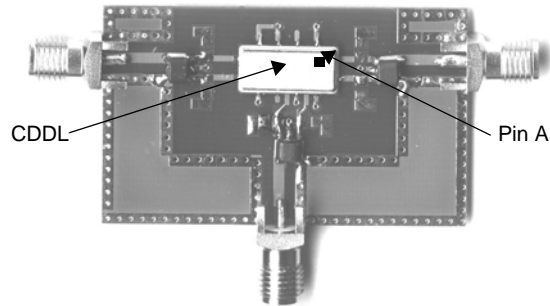


Figure 8: Test board used by Nanotron with 3 baluns (ETC1-1-13, Impedance ratio 1:1)

#### 3.2 Target Specifications and Measurement Results (03/2003)

Table 3: Measurement results

Parameter	Symbol	Conditions	Min	Typical	Max	Measured	Unit
Center Frequency <sup>1</sup>	$f_0$	–	247	250	253	249.51	MHz
Average insertion <sup>2</sup> loss without matching	–	$VSWR_{in}$ $SWR_{out}$	–	33	35	32.7	dB
3 dB bandwidth <sup>3</sup>	B	–	85	88	91	88.7	MHz
Average gradient of dispersion <sup>4</sup>	$K_d$	–	12.0	12.5	13.0	12.81	$\mu\text{s}/\text{GHz}$
Nominal group delay	$\tau_{\text{delay}}$	$= K_d B$	1.02	1.1	1.18	1.14	$\mu\text{s}$
Non-dispersive delay from input to one of the outputs <sup>5</sup>	$t_0$	$f_0$	700	750	800	760	ns
Non-disp. delay diff. between outputs <sup>6</sup>	$\tau$	$f_0$	–	10	60	13	ns
Number of delay lines on one substrate	–	–	–	2	–	2	–
Number of input ports	–	–	–	1	–	1	–
Number of output ports	–	–	–	2	–	2	–
Group delay for <sup>7</sup> delay line 1	$\tau_{g1(f)}$	–	–	$t_0 - K_d(f - f_0)$	–	–	$\mu\text{s}$
Group delay for <sup>8</sup> delay line 2	$\tau_{g2(f)}$	–	–	$t_0 + K_d(f - f_0)$	–	–	$\mu\text{s}$
Operating temperature range	$T_0$	–	-40	20	85	22	$^{\circ}\text{C}$

Table 3: Measurement results

Parameter	Symbol	Conditions	Min	Typical	Max	Measured	Unit
Difference in average insertion loss between both lines	–	at $f_0$ , $T_0=20^\circ\text{C}$	–	<3	–	1.3	dB
Average <sup>9</sup> VSWR input	VSWR <sub>in</sub>	$R_0, T_0$	–	20	40	20.19	–
Average <sup>10</sup> VSWR output	VSWR <sub>out</sub>	$R_0, T_0$	–	30	50	27.92	–
Source and load impedance	$R_0$	–	–	50	–	50	$\Omega$
Dimension of the chip	–	–	–	1.2 x 6.5	–	1.2 x 6.5	mm <sup>2</sup>
Dimensions of the housing	–	–	–	6.5 x 13.3	–	6.5 x 13.3	mm <sup>2</sup>

1. The center frequency of the CDDL is the common center frequency of both test signals (up-chirp and down-chirp) for which the run time difference of the compressed pulses is equal.
2. The averaging is done over the signal bandwidth from 210 to 290 MHz.
3. Referred to average insertion loss.
4. The gradient of dispersion includes always Fresnel ripples; therefore, the average (linear interpolation) is decisive.
5. Delay of a compressed pulse relative to the center position of the incoming chirp signal. This parameter is most sensitive against changes of temperature. Therefore a large range is specified.
6. See footnote 5.
7. This is most important to distinguish between the respective output ports of the 3 ports in Figure 1: <Emphasis Footnote>"Complementary Dispersive Delay Line schematic" on page 1–1.
8. See footnote 7.
9. The averaging is done over the signal bandwidth from 210 to 290 MHz.
10. See footnote 9.

## 4 Absolute Maximum Ratings

Table 1: Absolute maximum ratings

Parameter	Value	Units
Maximum RF power applied	20	dBm
<b>Temperatures</b>		
Operating temperature (operating ambient temperature range)	+85	°C
Storage temperature (storage temperature range)	+125	°C
Reflow solder temperature (lead-free package)	242	°C



It is critical that the ratings provided in *Absolute Maximum Ratings* on page 8 be carefully observed. Stress exceeding one or more of these limiting values may cause permanent damage to the device.

## 5 Tape and Reel Information

An embossed tape and reel is used to facilitate automatic pick and place equipment feed requirements. The tape is used as the shipping container for the CDDL and requires a minimum of handling. The antistatic/conductive tape provides a secure cavity for the product when sealed with the peel-back cover tape.

### 5.1 Reel Dimensions

- Reel diameter: 13 inches ( $328 \pm 2$  mm)
- Hub diameter: 5 inches (13 mm)
- Units per reel: 2,500

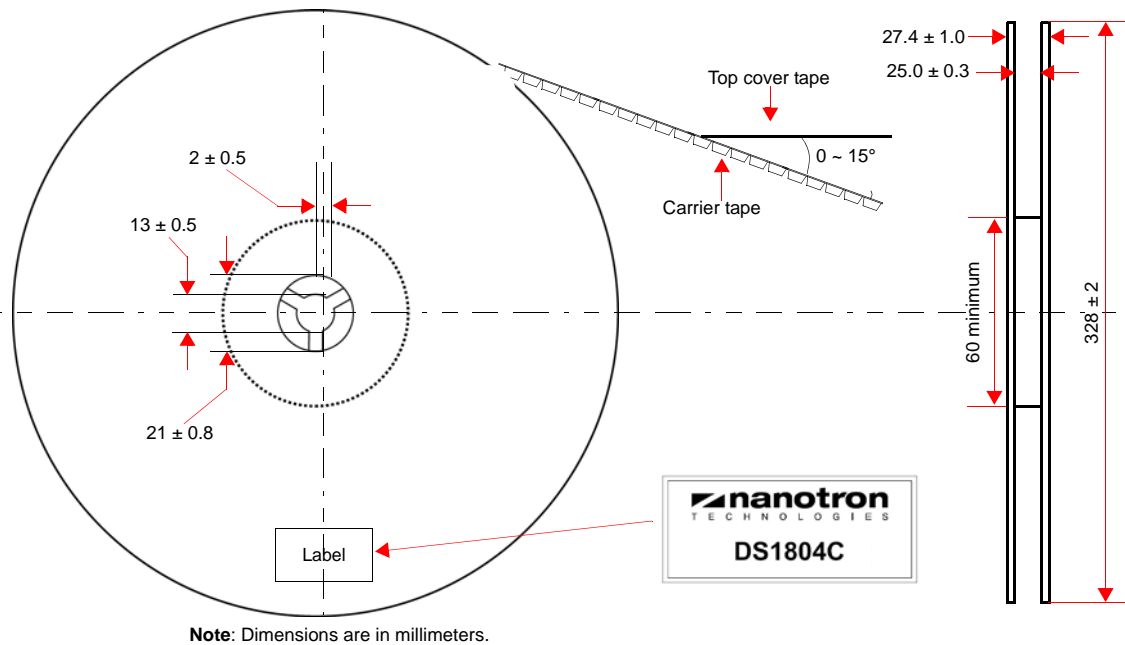


Figure 9: Reel dimensions

### 5.2 Tape Dimensions

#### 5.2.1 Tape Specifications

1. Tensile strength of carrier tape: 4.4N/mm width
2. Top cover tape adhesion:
  - Pull off angle: 0~15°
  - Speed: 300 mm / minute
  - Force: 20~70g

**5.2.2 Tape Running Direction**

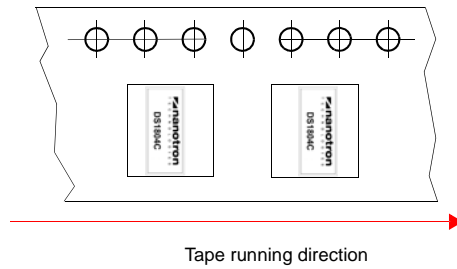


Figure 10: Tape running direction

**5.2.3 Leader Part and Vacant Position Specifications**

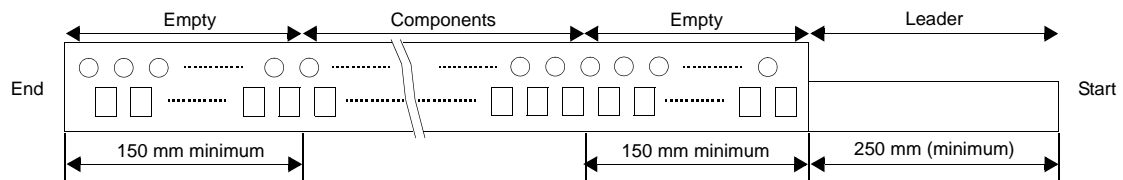


Figure 11: Tape leader and vacant positions specifications

**5.2.4 Tape Dimensions**

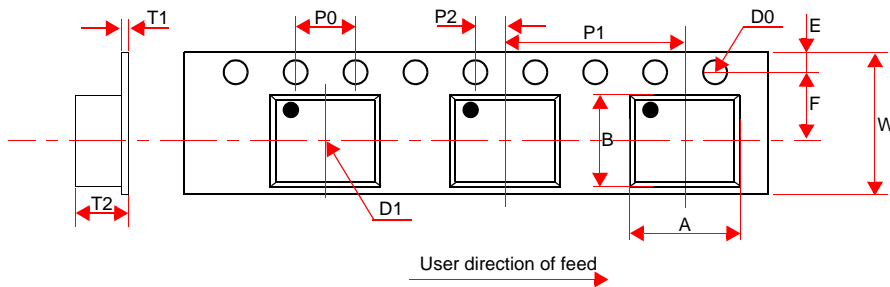


Figure 12: Tape dimensions

Table 4: Legend - tape dimensions (in millimeters)

W	F	E	P0	P1	P2	D0	D1	T1	T2	A	B
24.0	11.5	1.75	4.0	12.0	2.0	Φ 1.5	Φ 1.5	0.3	1.8	6.7	13.6
±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.25	±0.05	±0.1	±0.1	±0.1

## 6 Ordering Information

To order the product described in this document, use the following information.

*Table 2: Ordering information*

Part Number	Package Type	Package Quantity	RoHS Compliant
DS1804C	Tape and reel	2,500 pieces per tape	Yes. A certificate of RoHS compliance is available from Nanotron Technologies on request.

Intentionally Left Blank



## Revision History

Version	Date	Description/Changes
2.00	2004-04-07	<p>Picture of test board added            Target specification copied from document            NA-02-0143-0135-1.00            Measurement data copied from document            NA-03-0143-0216-1.00            Specified data from VSWR input and output exchanged            the type and measured size of die and package are now equal            temperature range changed from -20..+70 to the values of TRX chip -40..85            Center frequency changed:            Date of copy right actualized to 2004            Numbering of figures added            back ground printing "confidential &amp; preliminary" removed            Filter size in scale 10:1            Pad landing in scale 10:1            Pad landing area for pin 1 increased</p>
3.00	2004-04-26	<p>Changes in simulation of gradient of dispersion.            The notation of the pins is changed. At all ports the P and N part is exchanged,            to be compatible with current board layout nanoNET_TRX_module_V5.brd.</p>
4.00	2004-05-13	<p>Additional chapter for average insertion loss.            New value for av. insert. loss in table.            Last sentence in chapter 4.4 changed</p>
4.01	2004-07-20	<p>Package dimensions added.</p>
4.02	TBD	<p>Document template updated. Absolute maximum ratings added; packing information added; ordering information added; CDDL notation standardized; minor textual changes; company address updated.</p>
5.00	2007-08-21	<p>Minor Corrections to text and graphics. Minor editing throughout.</p>

## About Nanotron Technologies GmbH

*Nanotron Technologies GmbH* develops world-class wireless products for demanding applications based on its patented Chirp transmission system - an innovation that guarantees high robustness, optimal use of the available bandwidth, and low energy consumption. Since the beginning of 2005, Nanotron's Chirp technology has been a part of the IEEE 802.15.4a draft standard for wireless PANs which require extremely robust communication and low power consumption.

ICs and RF modules include *nanoNET TRX Transceiver*, *nanoLOC TRX Transceiver*, and ready-to-use or custom wireless solutions. These include, but are not limited to, industrial monitoring and control applications, medical applications (Active RFID), security applications, and Real Time Location Systems (RTLS). *nanoNET* is certified in Europe, United States, and Japan and supplied to customers worldwide.

Headquartered in Berlin, Germany, *Nanotron Technologies GmbH* was founded in 1991 and is an active member of IEEE and the ZigBee alliance.

### Further Information

For more information about this product and other products from Nanotron Technologies, contact a sales representative at the following address:

Nanotron Technologies GmbH  
Alt-Moabit 60  
10555 Berlin, Germany  
Phone: +49 30 399 954 - 0  
Fax: +49 30 399 954 - 188  
Email: [sales@nanotron.com](mailto:sales@nanotron.com)  
Internet: [www.nanotron.com](http://www.nanotron.com)